



# N-Channel 30 V (D-S) MOSFET

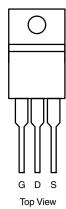
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)	
30	0.0051 at $V_{GS} = 10 \text{ V}$	50 <sup>d</sup>	21.7	
30	$0.0063$ at $V_{GS} = 4.5 \text{ V}$	50 <sup>d</sup>	21.7	

## **FEATURES**

- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
  - Material categorization: For definitions of compliance please see www.vishav.com/doc?99912



#### TO-220AB

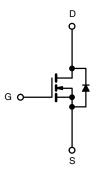


#### **Ordering Information:**

SUP50N03-5m1P-GE3 (Lead (Pb)-free and Halogen-free)

### **APPLICATIONS**

- Power Supply
  - Secondary Synchronous Rectification
- DC/DC Converter



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b>	$T_C = 25  ^{\circ}C$ , unless ot	herwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
Continuous Drain Current /T 150 °C)	T <sub>C</sub> = 25 °C	1	50 <sup>d</sup>	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 70 °C	l <sub>D</sub>	50 <sup>d</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	100	_ ^	
Avalanche Current		I <sub>AS</sub>	40	
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	80	mJ
	T <sub>C</sub> = 25 °C		59.5 <sup>b</sup>	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	P <sub>D</sub>	2.7	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	-55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	46	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.1	O/ <b>VV</b>		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

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# SUP50N03-5m1P

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			•	1			
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	30			.5 V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		2.5		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Drain-Source On-State Resistance <sup>a</sup>	B- ac	$V_{GS} = 10 \text{ V}, I_D = 22 \text{ A}$		0.0042	0.0051		
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0052	0.0063	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		110		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			2780			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$		641		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			260			
Tatal Cata ChausaC	Qa	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$	20 A 44	66			
Total Gate Charge <sup>c</sup>	₩g			21.7	32.6	~^	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		7		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			6.7			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.7	3.5	7	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_1 = 1.5 \Omega$		9	18		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		35	53	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18		
Drain-Source Body Diode Ratings a	nd Characteris	stics T <sub>C</sub> = 25 °C <sup>b</sup>		•			
Continuous Current	Is				50	۸	
Pulsed Current	I <sub>SM</sub>	<del></del>			100	Α	
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.75	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			34	51	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	$I_F = 10 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		2	3	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			34	51	nC	

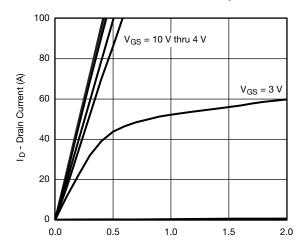
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

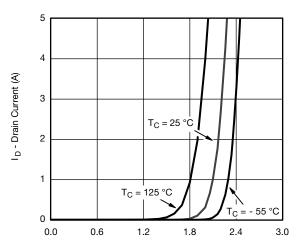
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



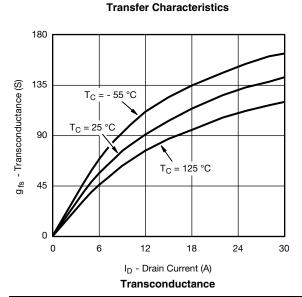
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

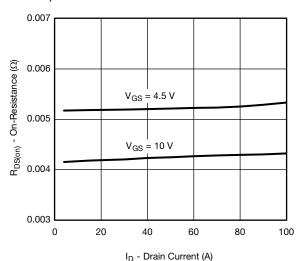


 $V_{DS}$  - Drain-to-Source Voltage (V) **Drain to Source Voltage vs. I\_D** 

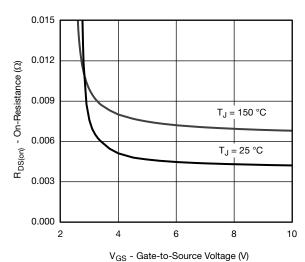


V<sub>GS</sub> - Gate-to-Source Voltage (V)

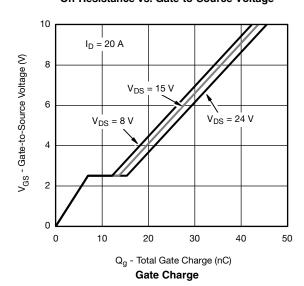




On-Resistance vs. Drain Current



On-Resistance vs. Gate-to-Source Voltage

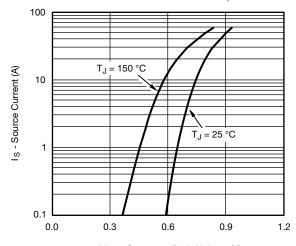


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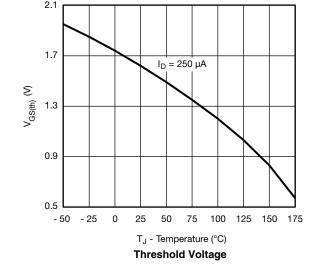
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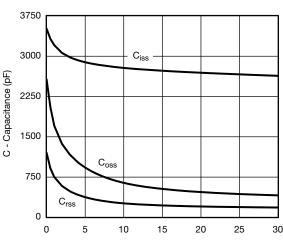


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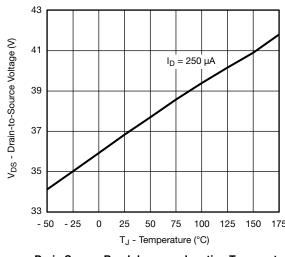


V<sub>SD</sub> - Source-to-Drain Voltage (V) Source-Drain Diode Forward Voltage

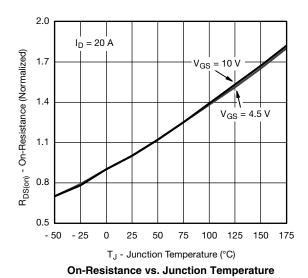


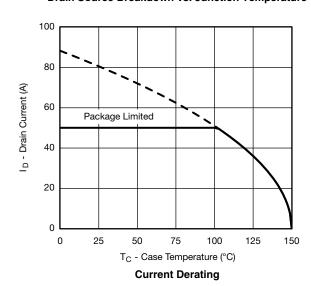


V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance



Drain Source Breakdown vs. Junction Temperature

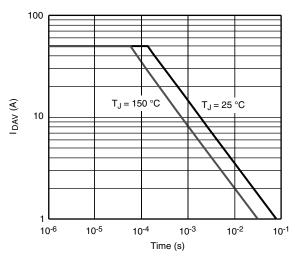


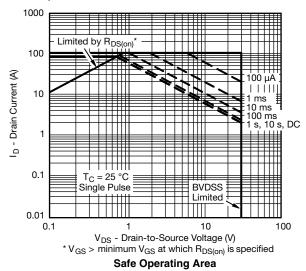




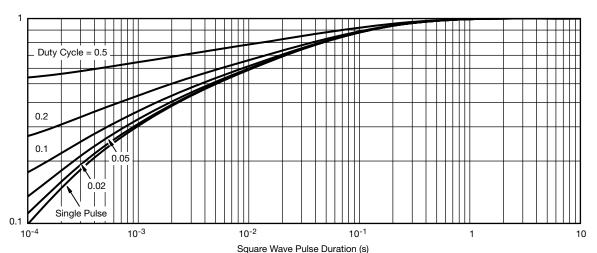
Normalized Effective Transient Thermal Impedance

### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time



Normalized Thermal Transient Impedance, Junction-to-Case

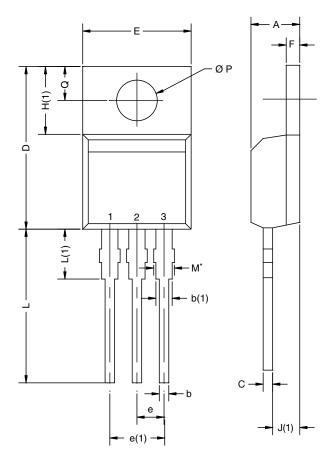
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## **TO-220AB**



	D2

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

#### Note

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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